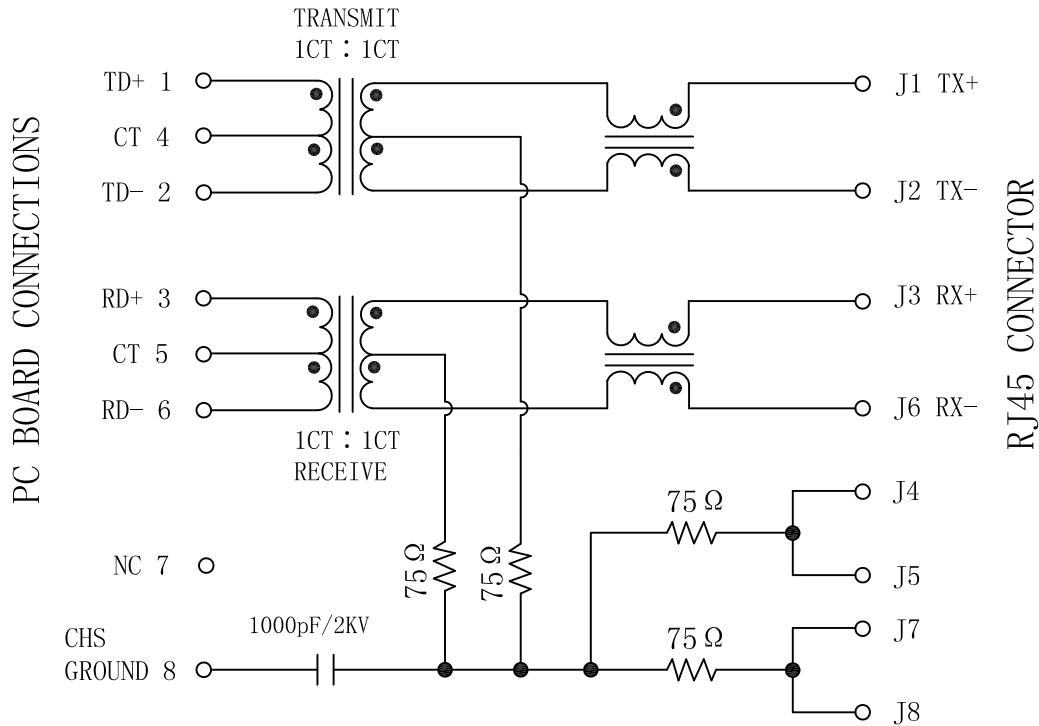


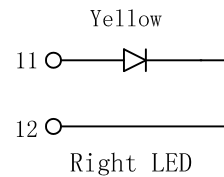
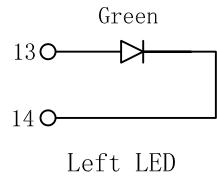
Schematic:

REV.	ECN NO.	DESCRIPTION	DATE	APPD
A	REL		2013-12-28	



ELECTRICAL SPECIFICATIONS @25°C

- Turn Ratio($\pm 3\%$):
TX=1CT:1CT RX=1CT:1CT
- Inductance OCL:
350uH MIN @ 100KHz 0.1V 8mA DC Bias
- Insertion Loss:
-1.0dB MAX @ 1-100MHz
- Return Loss:
-18dB MIN @ 1-30MHz
-15dB MIN @ 30-60MHz
-12dB MIN @ 60-100MHz
- Cross talk:
-40dB MIN @ 30MHz
-35dB MIN @ 60MHz
-30dB MIN @ 100MHz
- Common Mode Rejection:
-30dB MIN @ 1-100MHz
- Hipot Test: 1500Vrms
- Operating Temperature Range: -40°C TO +85°C

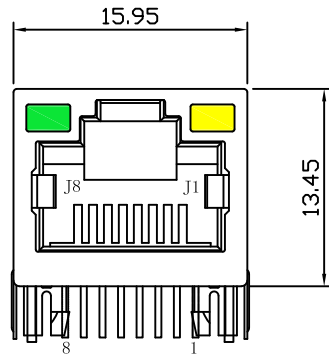


Emitting Color	λ_p (nm)	V _F @I _F =20mA	I _R @V _R =5V
Green	570	1.8~2.6V	10 μ A max
Yellow	585	1.8~2.6V	10 μ A max

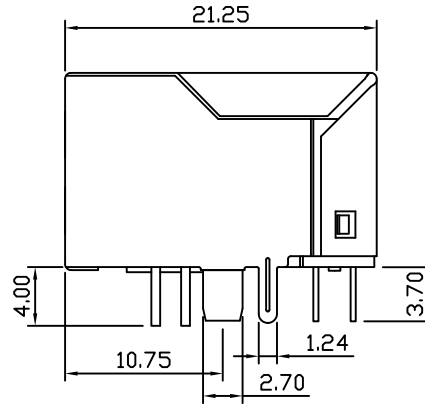
X:X	± 0.25	APPD:	LINK-PP INT'L TECHNOLOGY CO., LIMITED	
X:XX	± 0.20	CHKD:	TITLE: RJ45 Connector with 10/100 Base-T Integrated Magnetics	
X:XXX	± 0.05	DR: TOM	PART NO.: LPJ16611BENL	
ANGLES	$\pm 1^\circ$	UNIT: mm	DWG NO.: LP13122850	
		SCALE: 2/1	SHEET: 1/2	REV: A

Mechanical:

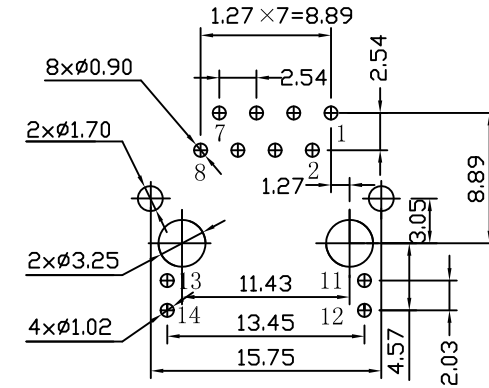
REV.	ECN NO.	DESCRIPTION	DATE	APPD
A	REL		2013-12-28	



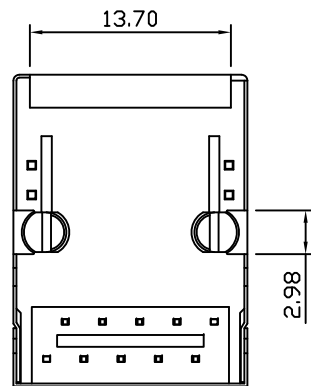
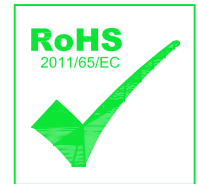
Front Side View



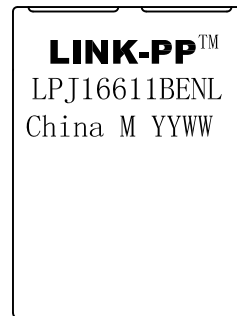
Left Side View



Suggested PCB Layout (Top View)



Bottom Side View



Top Side View

NOTES:

1. Meets IEEE 802.3 specification
2. Connector Materials:
 - Housing Material: Thermoplastic PBT+30%G.F UL94V-0
 - Contact Material: Phosphor Bronze C5210R-EH Thickness=0.35mm
 - Pins: Brass C2680R-H Thickness=0.35mm
 - Shield: SUS 201-1/2H Thickness=0.2mm
 - Contact plating: Gold 6 micro-inches min. In contact area.
3. Wave solder tip temperature: 265°C Max, 5 Sec Max

X:X	±0.25	APPD:	LINK-PP INT'L TECHNOLOGY CO., LIMITED	
X:XX	±0.20	CHKD:	TITLE: RJ45 Connector with 10/100 Base-T Integrated Magnetics	
X:XXX	±0.05	DR: TOM	PART NO.: LPJ16611BENL	
ANGLES	±1°	UNIT: mm	DWG NO.: LP13122850	
	SCALE: 2/1	SHEET: 2/2	REV: A	